

VARIATIONS (ALL DIMENSIONS IN MILLIMETERS)						
SYMBOL	VARIATION AA					
	MINIMUM	NOMINAL	MAXIMUM	NOTE		
A	---	---	1.85	7		
A2	1.45	1.50	1.55			
b	0.13	---	0.23	10, 11		
b1	0.13	0.16	0.19	10		
c	0.09	---	0.18	10		
c1	0.09	0.125	0.135	10		
D	27.00 BASIC			3		
E	13.00 BASIC			3		
E1	11.85 BASIC			3		
E2	10.15 BASIC			5		
e	0.40 BASIC					
F	9.40	9.50	9.60	13		
L	0.40	0.50	0.60			
R	0.12	---	0.30			
R1	0.70	0.75	0.80	13		
R2	---	---	1.05	13		
ZD	0.90 REF					
N	64			12		
NOTE	1, 2					
REF	11-514					
ISSUE	A					
TOLERANCES OF FORM AND POSITION						
aaa	0.07					
NOTE	1, 2					
REF	11-514					
ISSUE	A					
JEDEC SOLID STATE PRODUCT OUTLINES		TITLE: HORIZONTAL STAGGERED SURFACE MOUNT PACKAGE 0.40 mm LEAD PITCH R-PZIP-G64	ISSUE: A	DATE: NOV 98	MO-213	PAGE: 3 OF 4

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSIONS E, E1, AND D DO NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS. MOLD PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.

4. PIN NUMBERS ARE FOR REFERENCE ONLY.

5. DIMENSION E2 DOES NOT INCLUDE INTERLEAD MOLD PROTRUSION. INTERLEAD MOLD PROTRUSIONS SHALL NOT EXCEED 0.25mm.

6. SIZE OF THIS FEATURE MUST MATCH PACKAGE OUTLINE BODY SIZE WITH A TOLERANCE OF $+0.00/-0.25$ PER SIDE.

7. HEATSINK TO BE OPTIONAL. WITH NO HEAT SINK PRESENT, 0.03 BASIC DIMENSION MUST BE MAINTAINED.

8. EXACT DESIGN OF THIS FEATURE IS OPTIONAL.

9. A PIN #1 IDENTIFIER SHALL BE LOCATED ADJACENT TO PIN #1 WITHIN THE ZONE INDICATED. DETAILS OF THE PIN #1 IDENTIFIER ARE OPTIONAL.

10. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.

11. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSIONS/INTRUSIONS. ALLOWABLE DAMBAR PROTRUSIONS SHALL NOT CAUSE THE LEAD TO BE WIDER THAN THE MAXIMUM b DIMENSION BY MORE THAN 0.05mm. ALLOWABLE DAMBAR INTRUSION SHALL NOT CAUSE THE LEAD TO BE NARROWER THAN THE MINIMUM b DIMENSION BY MORE THAN 0.07mm.

12. N IS THE MAXIMUM NUMBER OF LEADS.

13. THIS ALIGNMENT FEATURE IS OPTIONAL.

14. MICRON TECHNOLOGY HAS APPLIED FOR A PATENT THAT MIGHT APPLY TO THIS REGISTRATION. IF THIS PATENT DOES APPLY MICRON INTENDS TO COMPLY WITH JEDEC PATENT POLICY.

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